SURFACE PROTECTING FILM FOR SEMICONDUCTOR WAFER AND METHOD OF PROTECTING SEMICONDUCTOR WAFER USING THE SAME

ABSTRACT

The present invention is to provide a surface protecting film for a semiconductor wafer which can prevent breakage of the semiconductor wafer even when the semiconductor wafer is thinned to not more than 200 μm, and a method of protecting the semiconductor wafer using the protecting film.

The present invention relates to a surface protecting adhesive film for a semiconductor wafer comprising a base film having an adhesive layer formed on one surface thereof, wherein the base film comprises a layer (A) having a storage elastic modulus of from 1×10^7 Pa to 1×10^9 Pa at a temperature range of from 20°C to 180°C.